



TF2011M

High-Side and Low-Side Gate Driver

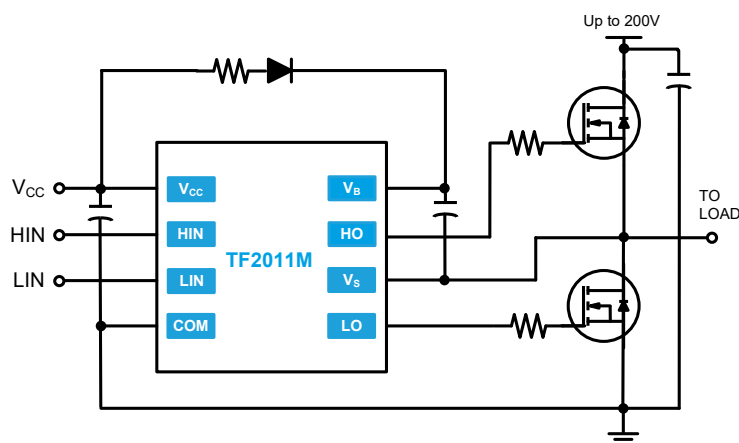
Features

- Floating high-side driver in bootstrap operation to 200V
- Drives two N-channel MOSFETs or IGBTs in a half bridge configuration
- 1.0A source / 1.0A sink output current capability
- Outputs tolerant to negative transients
- Wide low side gate driver supply voltage: 10V to 20V
- Logic input (HIN and LIN) 3.3V capability
- Schmitt triggered logic inputs with internal pull down
- Undervoltage lockout for high and low side drivers
- Extended temperature range: -40°C to +125°C

Applications

- DC-DC Converters
- AC-DC Inverters
- Motor Controls
- Class D Power Amplifiers

Typical Application



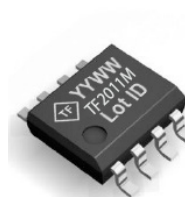
Description

The TF2011M is a high voltage, high speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. TF Semiconductor's high voltage process enables the TF2011's high side to switch to 200V in a bootstrap operation.

The TF2011M logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The TF2011M is offered in a SOIC-8(N) package and operates over an extended -40 °C to +125 °C temperature range.

SOIC-8(N)

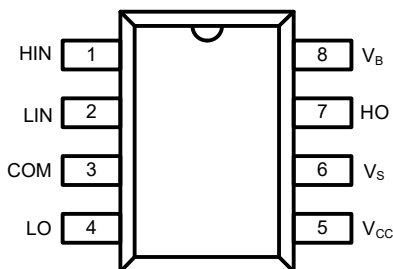


Ordering Information

PART NUMBER	PACKAGE	PACK / Qty	Year	Year	Week	Week
			Year	Year	Week	Week
TF2011M-TAU	SOIC-8(N)	Tube / 100	TF	YY	WW	TF2011M Lot ID
TF2011M-TAH	SOIC-8(N)	T&R / 2500				



Pin Diagrams

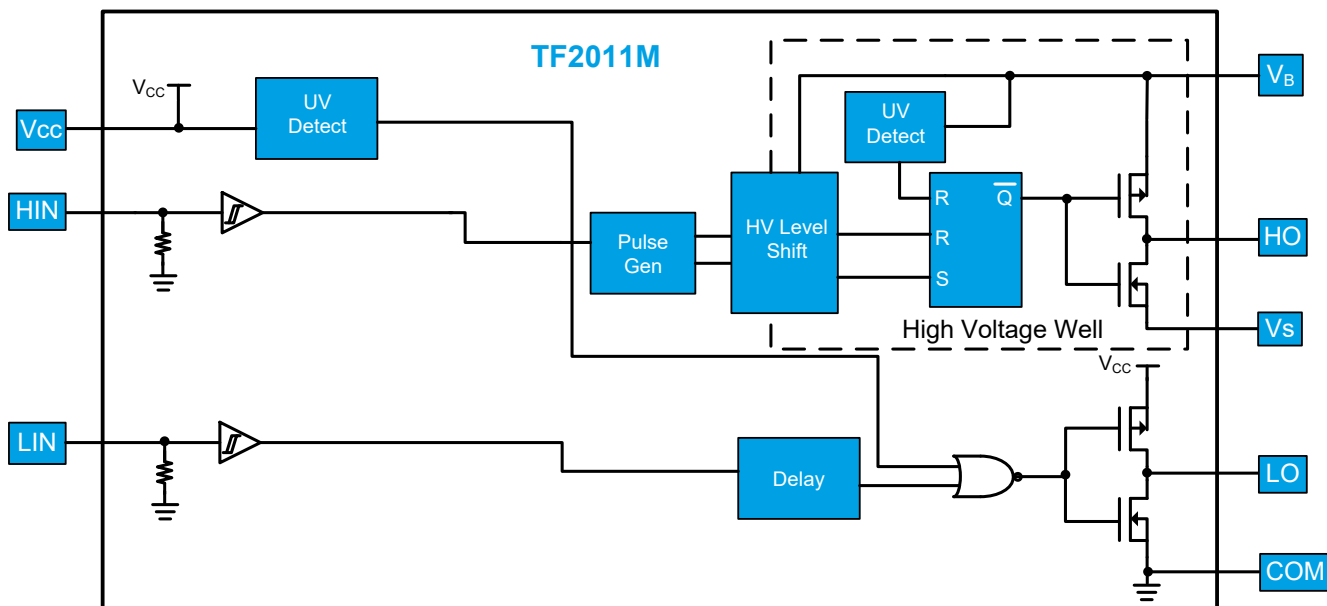


Top View: SOIC-8

Pin Descriptions

PIN NAME	PIN NUMBER	PIN DESCRIPTION
HIN	1	Logic input for high-side gate driver output, in phase with HO.
LIN	2	Logic input for low-side gate driver output, in phase with LO.
COM	3	Low-side and logic return
LO	4	Low-side gate drive output
V _{cc}	5	Low-side and logic fixed supply
V _s	6	High-side floating supply return
HO	7	High-side gate drive output
V _B	8	High-side floating supply

Functional Block Diagram





Absolute Maximum Ratings (NOTE1)

V_B - High side floating supply voltage.....-0.3V to +224V
 V_S - High side floating supply offset voltage... V_B -24V to V_B +0.3V
 V_{HO} - High side floating output voltage..... V_S -0.3V to V_B +0.3V
 dV_S/dt - Offset supply voltage transient.....50 V/ns

V_{CC} - Low-side fixed supply voltage.....-0.3V to +24V
 V_{LO} - Low-side output voltage.....-0.3V to V_{CC} +0.3V
 V_{IN} - Logic input voltage (HIN and LIN).....-0.3V to V_{CC} +0.3V

NOTE1 Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

P_D - Package power dissipation at $T_A \leq 25^\circ\text{C}$
 SOIC-8.....0.625W

SOIC-8(N) Thermal Resistance (NOTE2)

θ_{JA}200 $^\circ\text{C}/\text{W}$

T_J - Junction operating temperature.....+150 $^\circ\text{C}$
 T_L - Lead Temperature (soldering, 10 seconds).....+300 $^\circ\text{C}$
 T_{stg} - Storage temperature-55 to 150 $^\circ\text{C}$

NOTE2 When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Symbol	Parameter	MIN	MAX	Unit
V_B	High side floating supply absolute voltage	$V_S + 10$	$V_S + 20$	V
V_S	High side floating supply offset voltage	NOTE3	200	V
V_{HO}	High side floating output voltage	V_S	V_B	V
V_{CC}	Low side fixed supply voltage	10	20	V
V_{LO}	Low side output voltage	0	V_{CC}	V
V_{IN}	Logic input voltage (HIN and LIN)	0	5	V
T_A	Ambient temperature	-40	125	$^\circ\text{C}$

NOTE3 Logic operational for V_S of -5V to +200V.



DC Electrical Characteristics (NOTE4)

$V_{BIAS} (V_{CC}, V_{BS}) = 15V, T_A = 25\text{ }^\circ\text{C}$, unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
V_{IH}	Logic "1" input voltage	$V_{CC} = 10V$ to $20V$	2.5			V
V_{IL}	Logic "0" input voltage	NOTES			0.8	
V_{OH}	High level output voltage, $V_{BIAS} - V_O$	$I_O = 0A$			1.4	
V_{OL}	Low level output voltage, V_O	$I_O = 20mA$			0.2	
I_{LK}	Offset supply leakage current	$V_B = V_S = 200V$			50	μA
I_{BSQ}	Quiescent V_{BS} supply current	$V_{IN} = 0V$ or $5V$		60	150	
I_{CCQ}	Quiescent V_{CC} supply current	$V_{IN} = 0V$ or $5V$		120	240	μA
I_{IN+}	Logic "1" input bias current	$V_{IN} = 5V$		25	60	μA
I_{IN-}	Logic "0" input bias current	$V_{IN} = 0V$			5.0	
V_{BSUV+}	V_{BS} supply under-voltage positive going threshold		8.0	8.9	9.8	V
V_{BSUV-}	V_{BS} supply under-voltage negative going threshold		7.4	8.2	9.0	
V_{CCUV+}	V_{CC} supply under-voltage positive going threshold		8.0	8.9	9.8	
V_{CCUV-}	V_{CC} supply under-voltage negative going threshold		7.4	8.2	9.0	
I_{O+}	Output high short circuit pulsed current	$V_O = 0V, PW \leq 10\ \mu s$		1.0		A
I_{O-}	Output low short circuit pulsed current	$V_O = 15V, PW \leq 10\ \mu s$		1.0		

NOTE4 The V_{IH} , V_{IL} , and I_{IN} parameters are applicable to the two logic input pins: LIN and HIN. The V_O and I_O parameters are applicable to the respective output pins: HO and LO.

NOTES For optimal operation, it is recommended that the input pulse (to HIN and LIN) should have an amplitude of 2.5V minimum with a pulse width of 240ns minimum.



AC Electrical Characteristics

$V_{BIAS} (V_{CC}, V_{BS}) = 15V$, $C_L = 1000pF$, and $T_A = 25^\circ C$, unless otherwise specified.

Symbol	Parameter	Conditions	MIN	TYP	MAX	Unit
t_{on}	Turn-on propagation delay	$V_S = 0V$		120		ns
t_{off}	Turn-off propagation delay	$V_S = 0V$ or $200V$		120		
t_{DM}	Delay matching, HS & LS turn-on/off				20	
t_r	Turn-on rise time	$V_S = 0V$		30		
t_f	Turn-off fall time			30		



Timing Waveforms

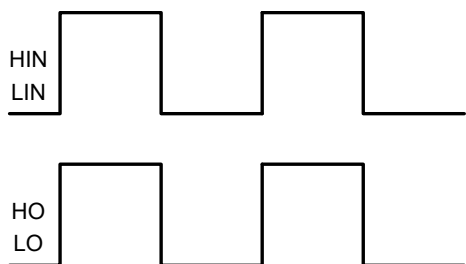


Figure 1. Input / Output Timing Diagram

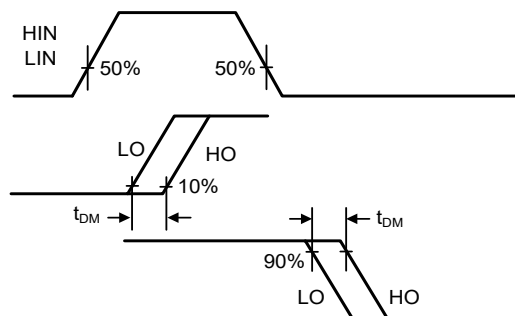


Figure 2. Delay Matching Waveform Definitions

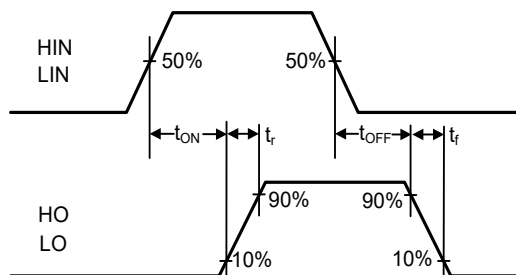


Figure 3. Switching Time Waveform Definitions



Application Information

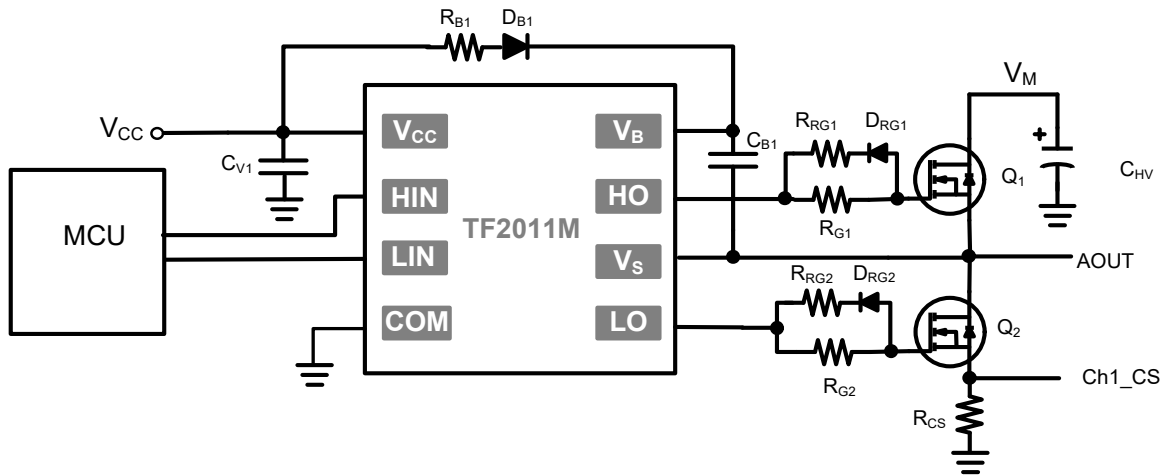


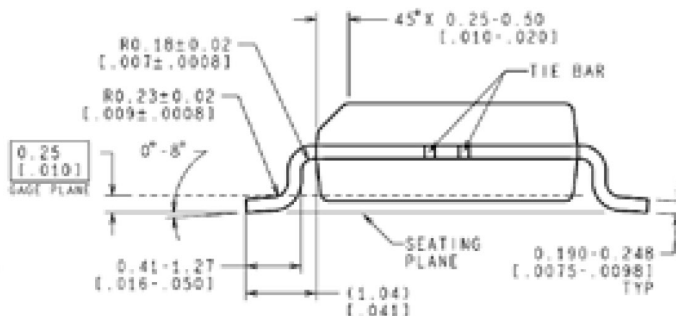
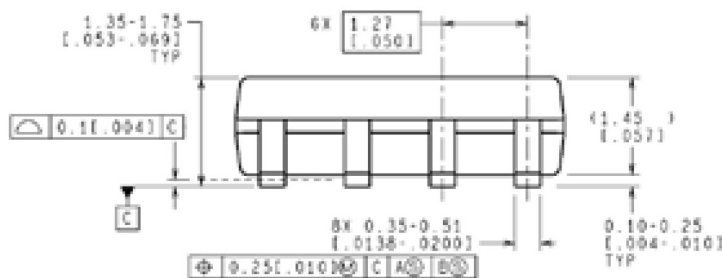
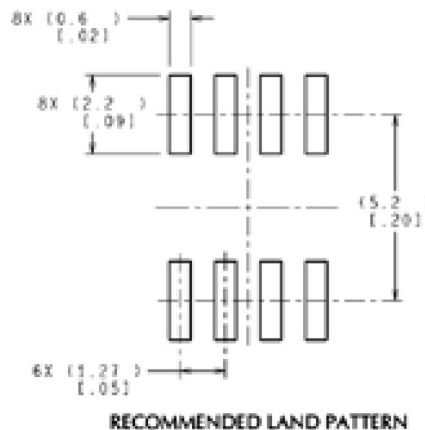
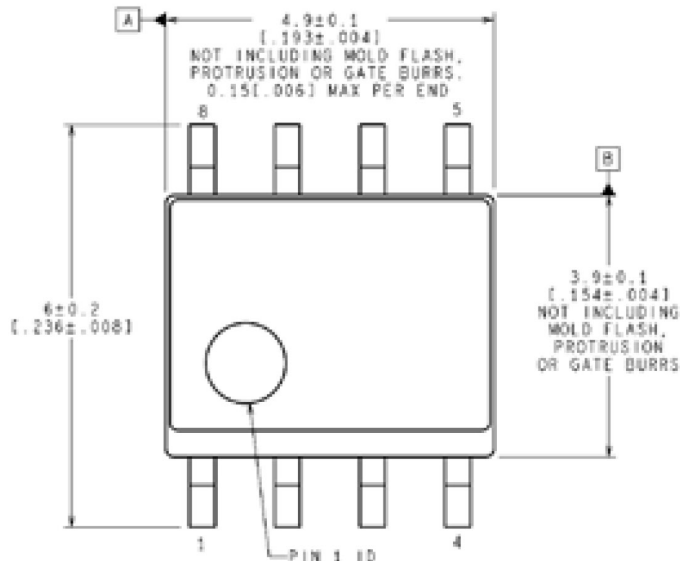
Figure 4. Single phase (of four) for Stepper motor driver application using the TF2011M

- RRG1 and RRG2 values are typically between 0Ω and 10Ω , exact value decided by MOSFET junction capacitance and drive current of gate driver; 10Ω is used in this example.
- RG1 and RG2 values are typically between 10Ω and 100Ω , exact value decided by MOSFET junction capacitance and drive current of gate driver; 50Ω is used in this example.
- RB1 value is typically between 3Ω and 20Ω , exact value depending on bootstrap capacitor value and amount of current limiting required for bootstrap capacitor charging; 10Ω is used in this example. Also DB should be an ultra fast diode of 1A rating minimum and voltage rating greater than system operating voltage.
- It is recommended that the input pulse (to HIN and LIN) should have an amplitude of 2.5V minimum (for VDD=15V) with a minimum pulse width of 240ns.



Package Dimensions (SOIC-8 N)

Please contact support@tfsemi.com for package availability.



NOTES: UNLESS OTHERWISE SPECIFIED

1. REFERENCE JEDEC REGISTRATION MS-012, VARIATION AA.

CONTROLLING DIMENSION IS MILLIMETER
VALUES IN [] ARE INCHES
DIMENSIONS IN () FOR REFERENCE ONLY



Revision History

Rev.	Change	Owner	Date
1.0	Initial release Advance Info document	Duke Walton	3/13/2021
1.1	Add Applications Information page.	Keith Spaulding	9/1/2022

Important Notice

TF Semiconductor Solutions (TFSS) PRODUCTS ARE NEITHER DESIGNED NOR INTENDED FOR USE IN MILITARY AND/OR AEROSPACE, AUTOMOTIVE OR MEDICAL DEVICES OR SYSTEMS UNLESS THE SPECIFIC TFSS PRODUCTS ARE SPECIFICALLY DESIGNATED BY TFSS FOR SUCH USE. BUYERS ACKNOWLEDGE AND AGREE THAT ANY SUCH USE OF TFSS PRODUCTS WHICH TFSS HAS NOT DESIGNATED FOR USE IN MILITARY AND/OR AEROSPACE, AUTOMOTIVE OR MEDICAL DEVICES OR SYSTEMS IS SOLELY AT THE BUYER'S RISK.

TFSS assumes no liability for application assistance or customer product design. Customers are responsible for their products and applications using TFSS products.

Resale of TFSS products or services with statements different from or beyond the parameters stated by TFSS for that product or service voids all express and any implied warranties for the associated TFSS product or service. TFSS is not responsible or liable for any such statements.

©2021 TFSS. All Rights Reserved. Information and data in this document are owned by TFSS wholly and may not be edited, reproduced, or redistributed in any way without the express written consent from TFSS.

For additional information please contact support@tfsemi.com or visit www.tfsemi.com.